

# Barrel TOF Layout (v0)

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# EIC Detector-1 Reference Design

## Tracking:

- Si MAPS
- **AC-LGAD**
- $\mu$ RWELL

## PID:

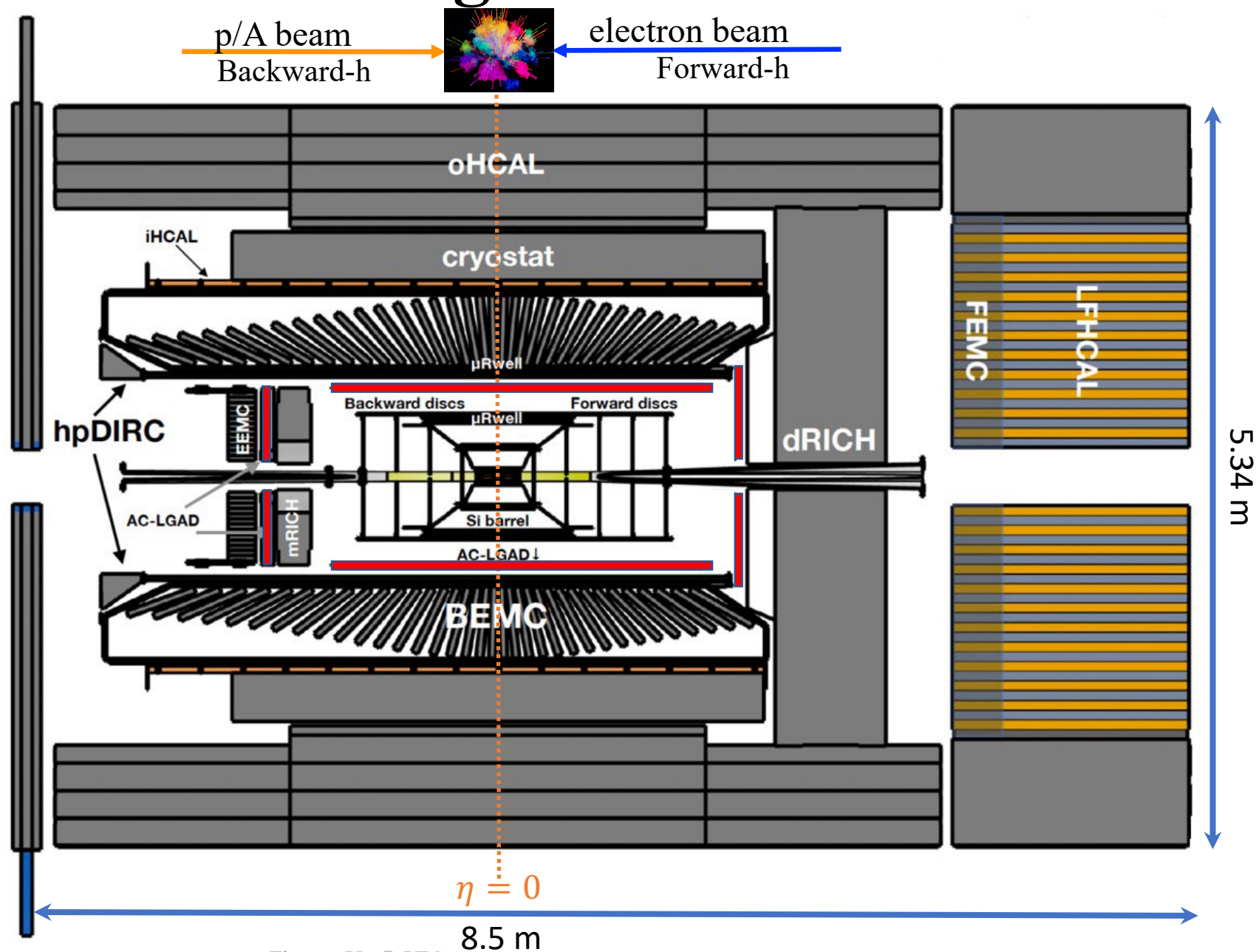
- hp-DIRC
- mRICH
- dRICH
- **AC-LGAD**

## Calorimetry:

- SciGlass Barrel EMCal
- PbWO EEMCal
- Longitudinally separated EM+Hcal
- Inner HCal (instrumented frame)
- Outer HCal (sPHENIX re-use)

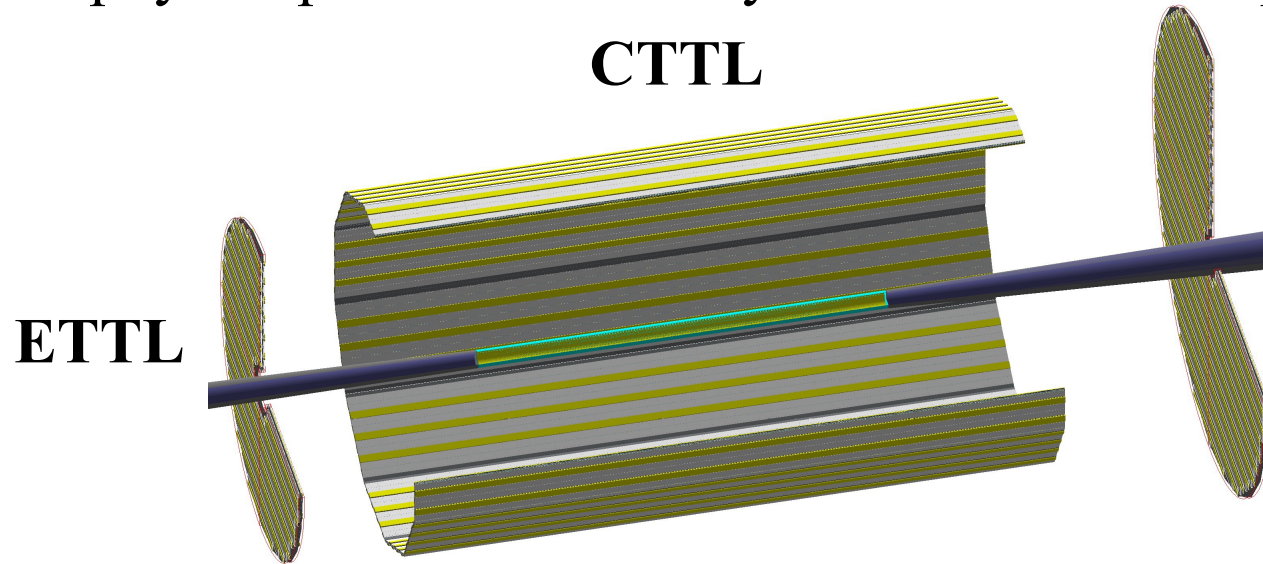
## Different to LHC

- lower momentum
- lower occupancy
- less irradiation



# AC-LGAD Layer for TOF PID + Tracking

- The goal is to conceive a reference layout and technical design (v0) as inputs to GD/I group to advance the detector integration (service routing etc.)
- However, there are still on-going studies to investigate the optimal channel granularity based on physics performance so by no means this is a proposal for final design.



FTTL

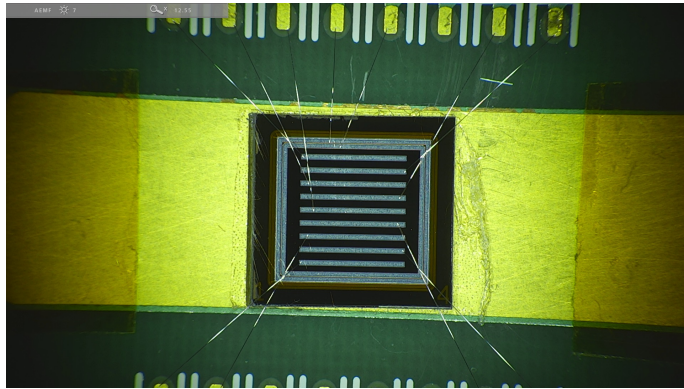
For v0 design, we propose:

- **Barrel: 0.5x10 mm<sup>2</sup> strips**
- **Endcap: 0.5x0.5 mm<sup>2</sup> pixels (same as RPs) [1]**

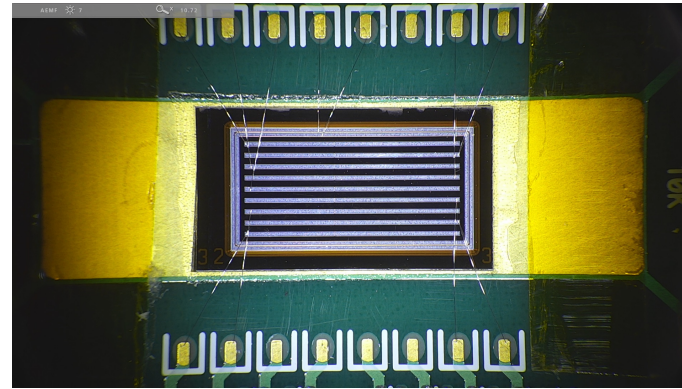
[1] Wei Li, TOF-PID WG Meeting Aug 29, 2022

	acceptance	Z (m)	Radius (m)	Area (m <sup>2</sup> )	Channel size (mm <sup>2</sup> )	# of Channels
ETTL	$-3.7 < \eta < -1.74$	-1.61 to -1.71	0.12 to 0.63	1.20	0.5*0.5	4.8M
CTTL	$ \eta  < 1.4$	-1.2 to 1.5	0.625 to 0.655	10.9	0.5*10	2.4M
FTTL	$1.5 < \eta < 3.5$	1.555 to 1.705	0.12 to 0.85	2.22	0.5*0.5	8.8M

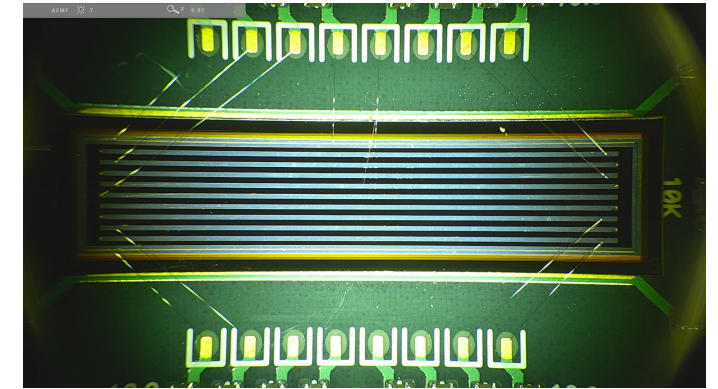
# Test Beam Results of Strip AC-LGAD Sensors



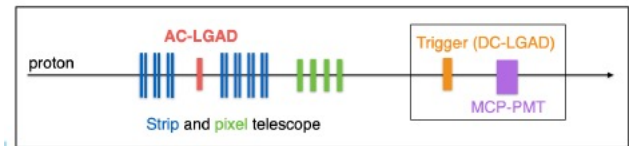
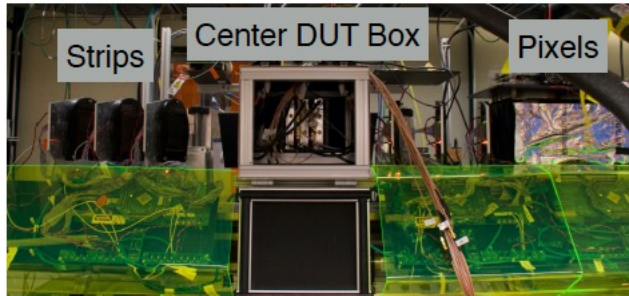
0.5\*5 mm<sup>2</sup>



0.5\*10 mm<sup>2</sup>



0.5\*25 mm<sup>2</sup>



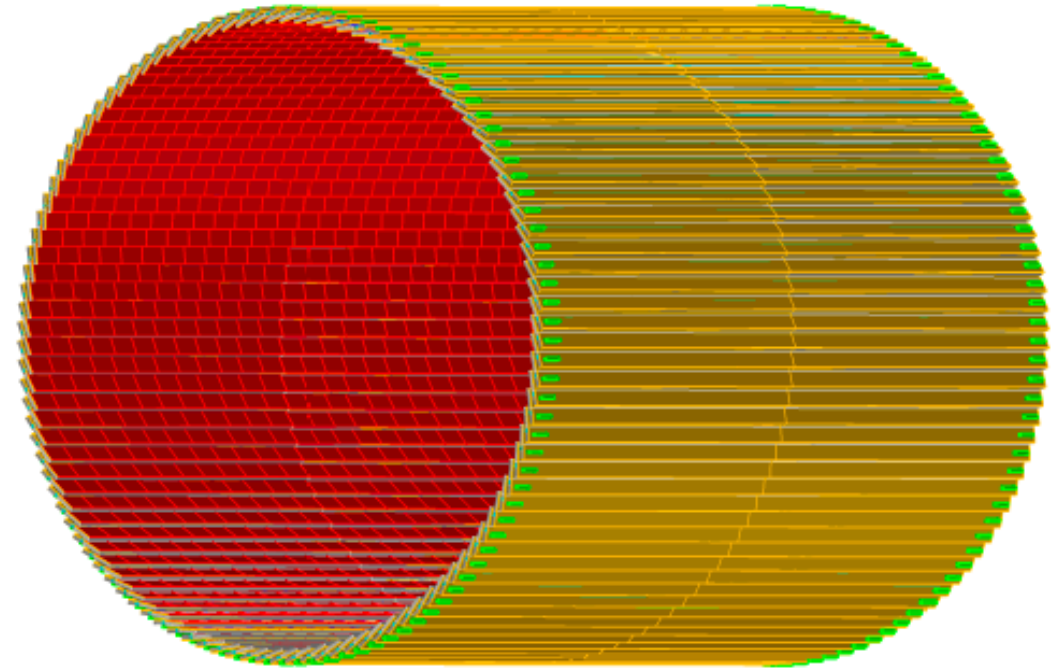
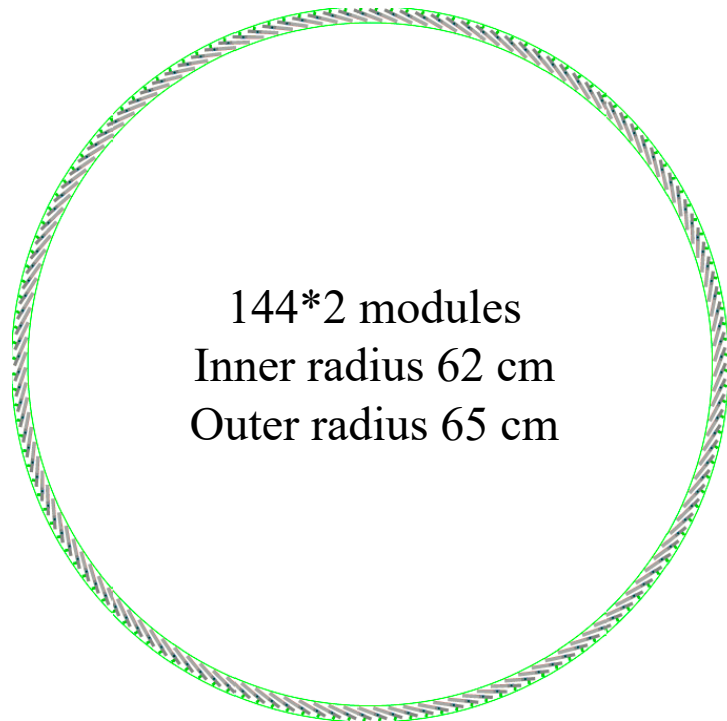
<b>Preliminary Results</b>	Time Resolution / hit	Position Resolution / hit
HPK-C2 Pixels 500 x 500 μm <sup>2</sup>	30 ± 1 ps	22 ± 1 μm
BNL Strips 500 μm x 5 mm	~ 30 ps (Hot spots)	< 15 μm
BNL Strips 500 μm x 10 mm	~ 32 ps (Hot spots)	< 20 μm
BNL Strips 500 μm x 25 mm	~ 53 ps (Hot spots)	< 40 μm

eRD112/LGAD Consortium meeting 8/3/2022 by Chris Madrid (FNAL)

<https://indico.bnl.gov/event/16500/>

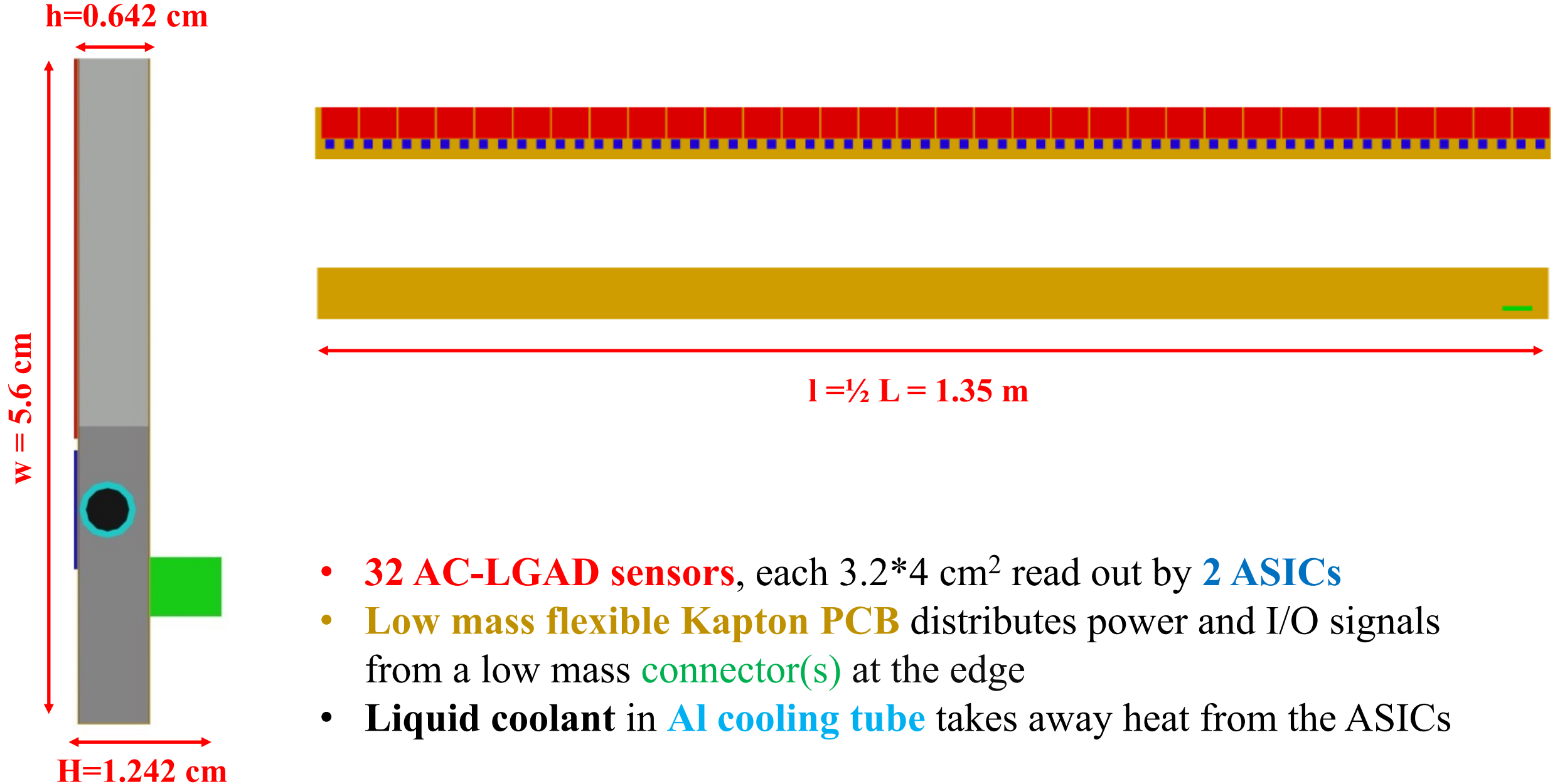
# Barrel TOF Layout and Specification

- **Single layer of strip AC-LGAD sensors**
    - $62 < R < 65$  cm, 2.7 m long,  $\sim 11$  m<sup>2</sup> area
  - **Strip metal electrodes, with  $500 \mu\text{m}$  pitch in  $r\phi$  and  $1 \text{ cm}^*$  in  $z$** 
    - Minimal material budget and power consumption compared to pixels
- \* Will look into longer strips with sensor R&D



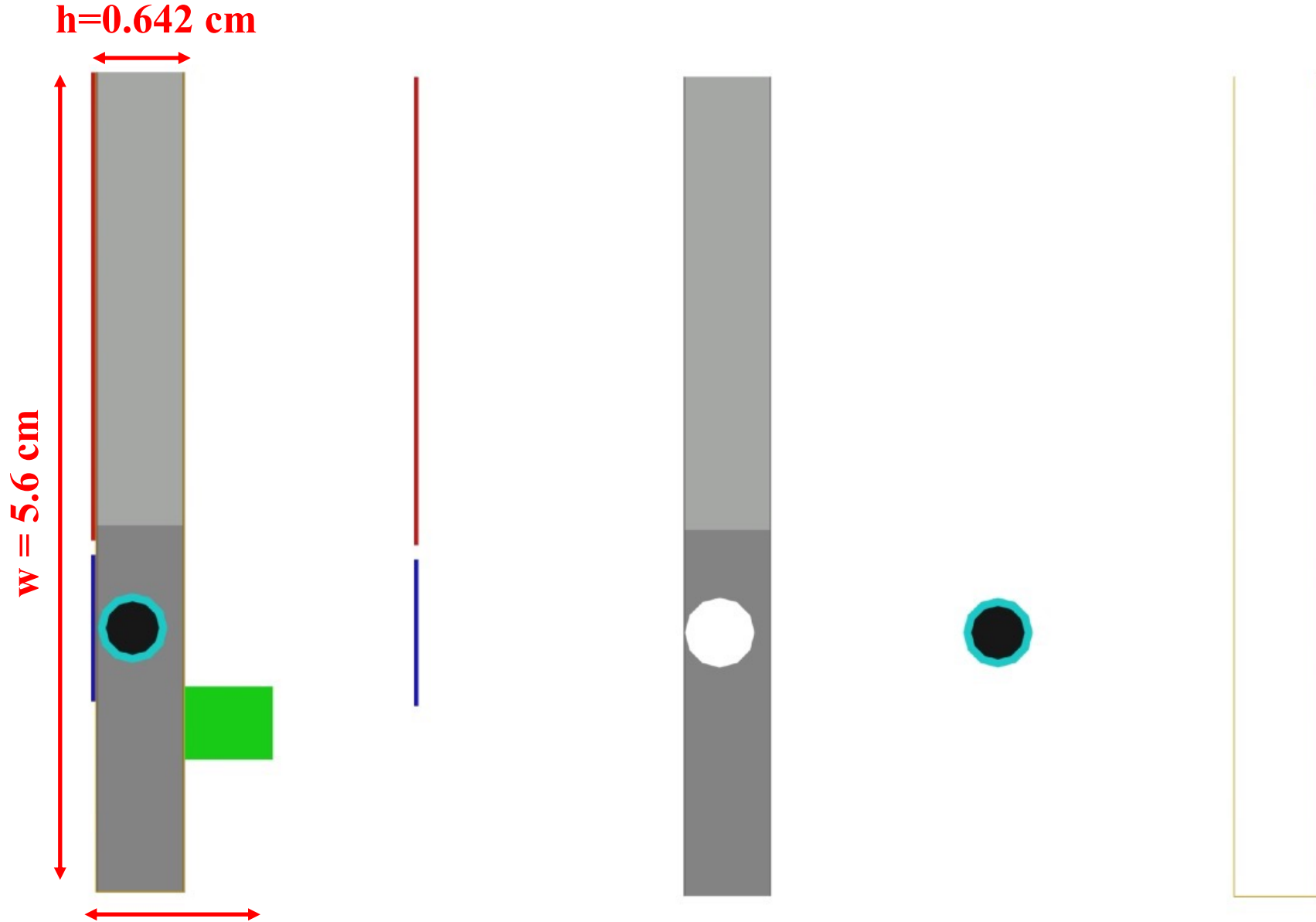
# EPIC Barrel TOF Module

>95% coverage in Z



- **32 AC-LGAD sensors**, each  $3.2 \times 4$  cm<sup>2</sup> read out by **2 ASICs**
- **Low mass flexible Kapton PCB** distributes power and I/O signals from a low mass **connector(s)** at the edge
- **Liquid coolant** in **Al cooling tube** takes away heat from the ASICs

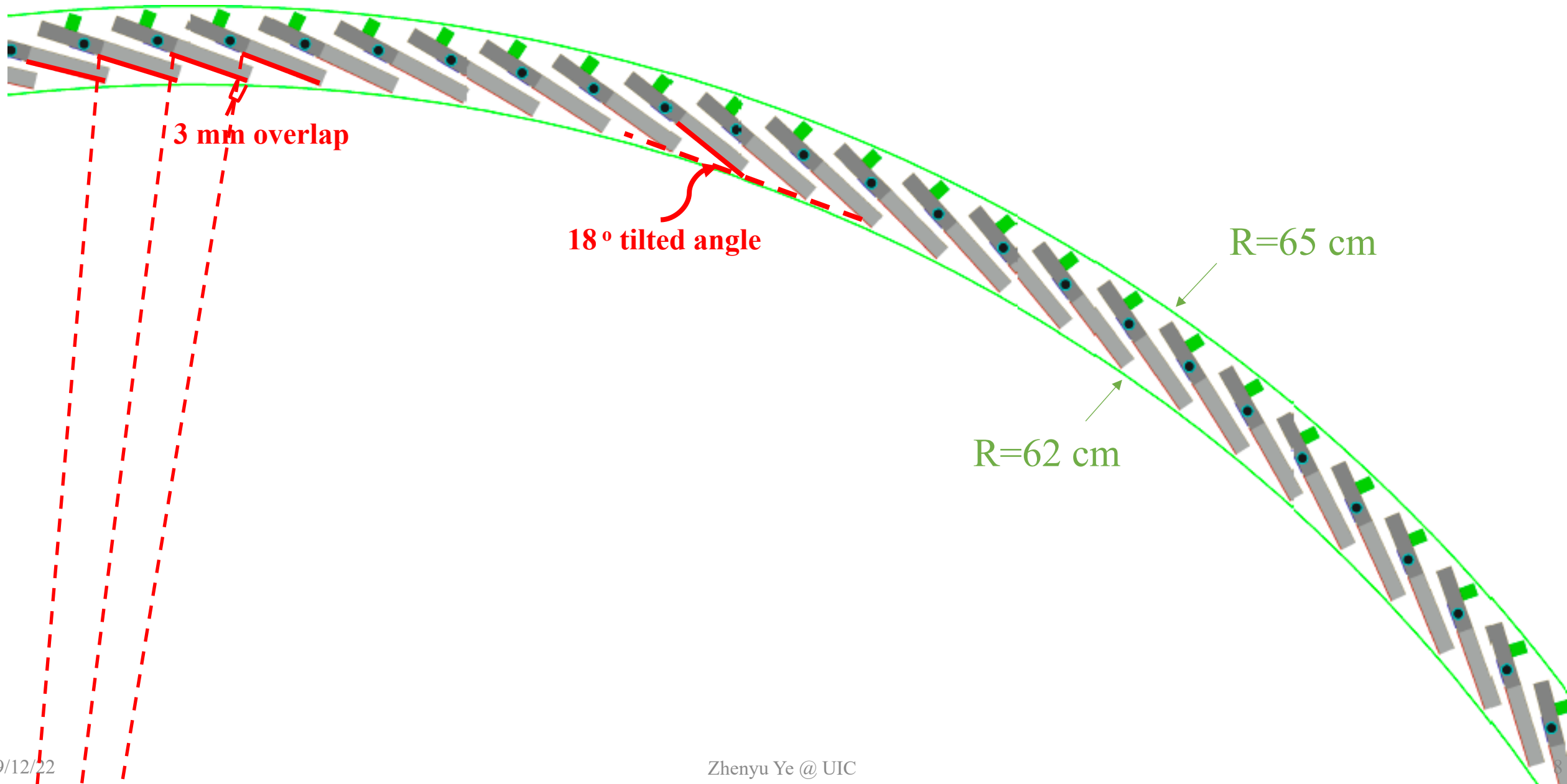
# EPIC Barrel TOF Module



- **AC-LGAD sensor**
- **Frontend ASICs**
- Carbon foam+  
Carbon honeycomb+  
**CF skins**
- **Al cooling tube**
- **Liquid coolant**
- **Kapton PCB**
- **Connector**

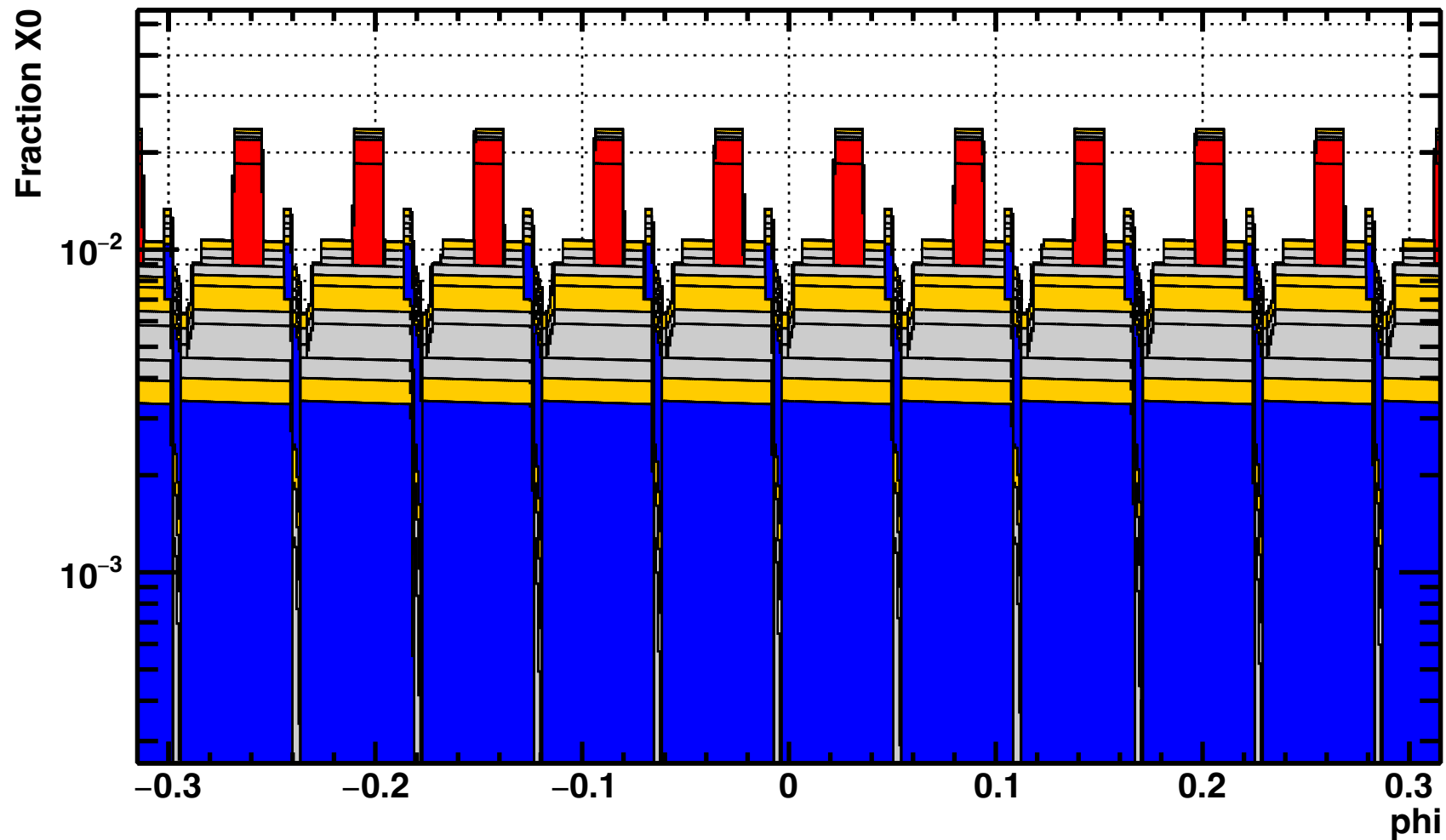
# EPIC Barrel TOF Detector Layout

Full azimuthal coverage





# Barrel TOF Material Budget

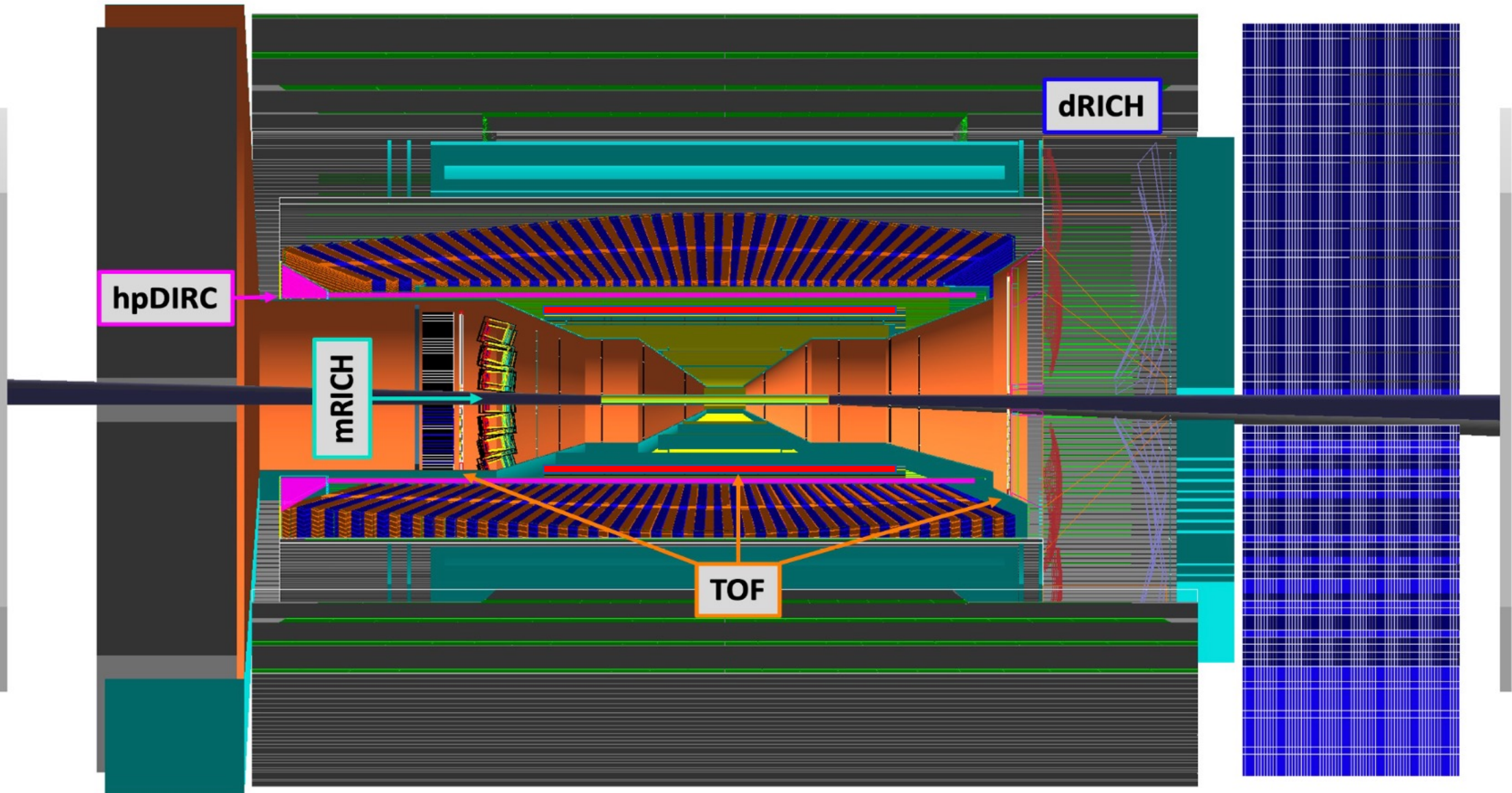


Average material budget  $\sim 1\% X_0$

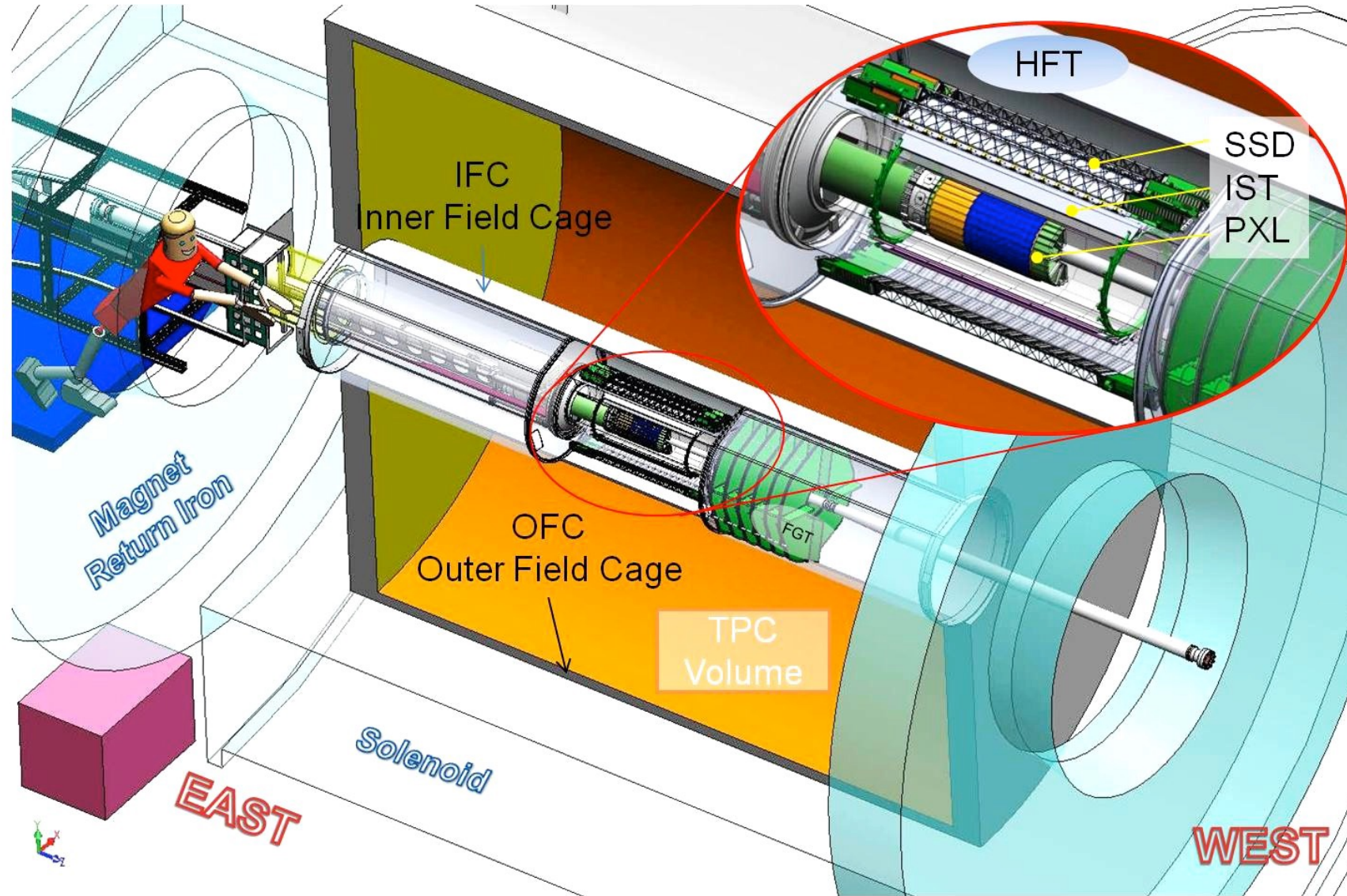
# Services

- In total 288 modules,
  - 9216 sensors, 18,432 ASICs, 2.4 M channels
  - $\sim 70$  kG,  $\sim 4$  kW
- On each module:
  - 32 sensors, 64 frontend ASIC
  - Powered and read out by 1 service board
  - 1 fiber to DAQ
  - 1 LV+HV cable
  - 1 liquid cooling line

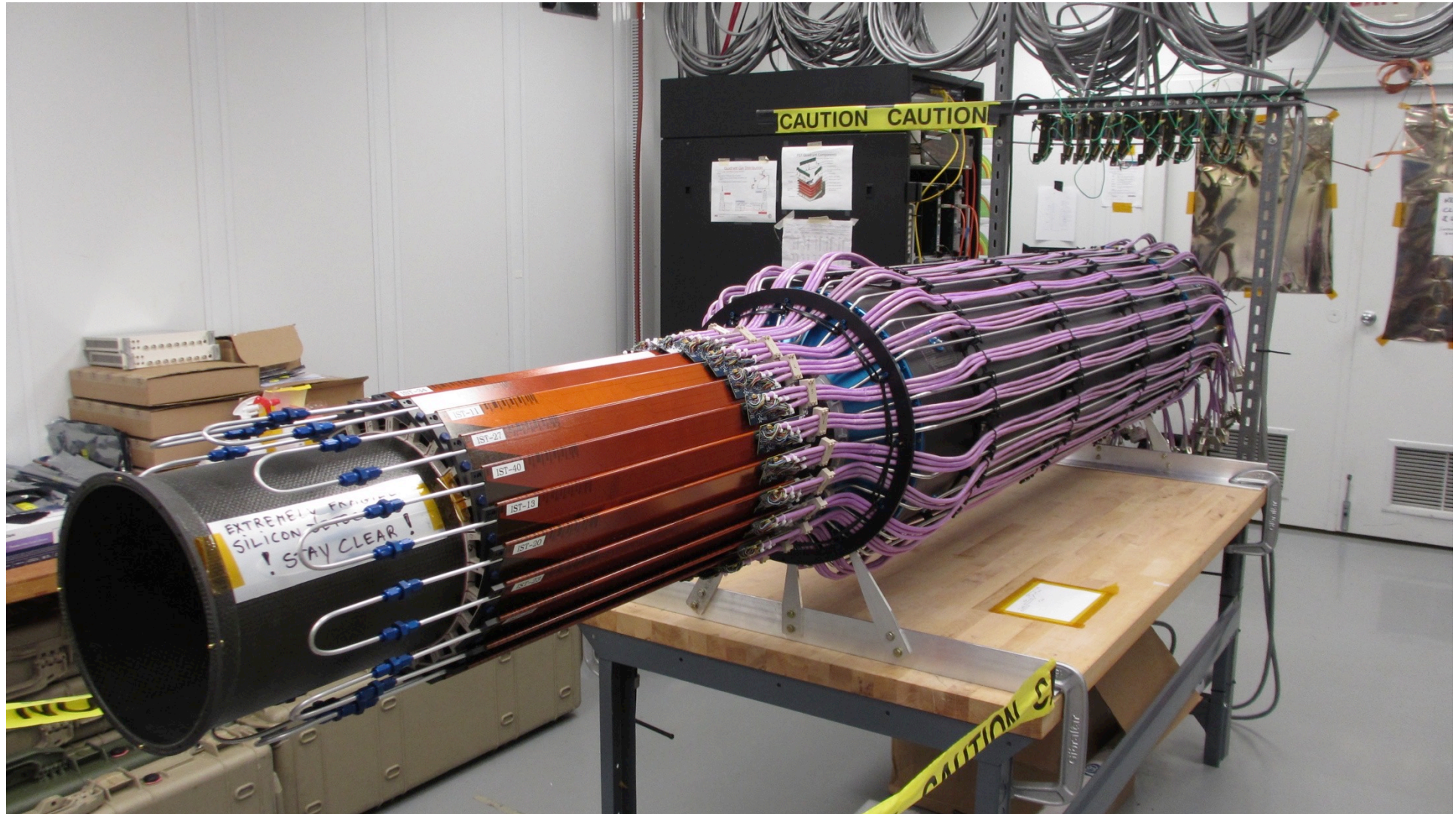
# Backup



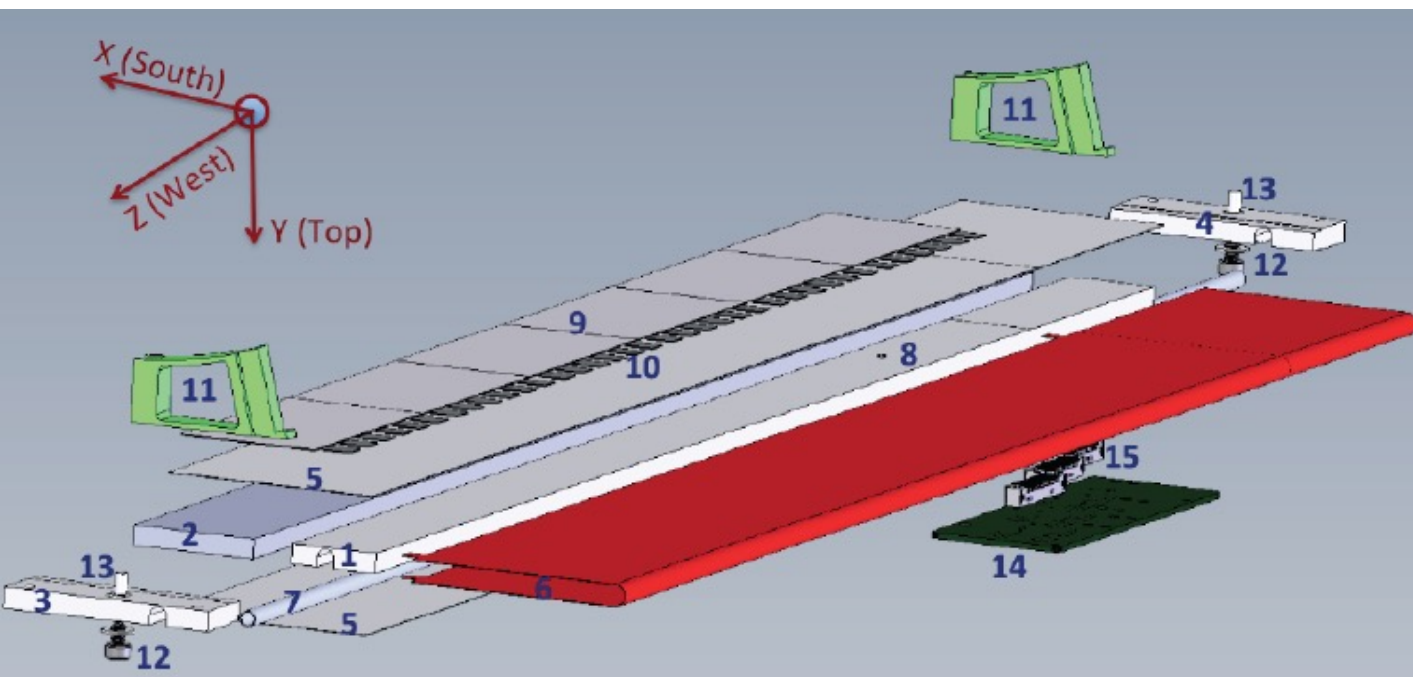
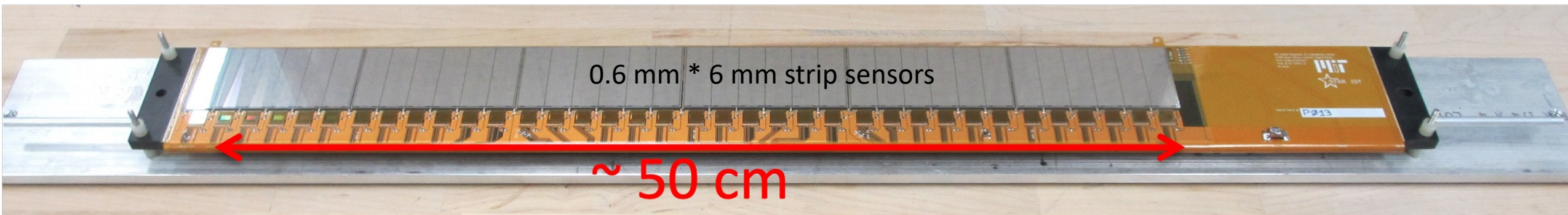
# STAR Intermediate Silicon Tracker



# STAR Intermediate Silicon Tracker



# STAR Intermediate Silicon Tracker



- 1) carbon foam
- 2) carbon honeycomb
- 3) west carbon end-cap
- 4) east Al end-cap
- 5) carbon fiber skins
- 6) Kapton hybrid
- 7) Al cooling tube with cooling liquid inside
- 8) thermal sensor
- 9) silicon sensors
- 10) APV chips
- 11) support blocks
- 12) screws with washers
- 13) spacers
- 14) transition board
- 15) readout connectors.

# STAR Intermediate Silicon Tracker

Material budget  $< 1\% X_0$

